

WIT-220 Wafer Optical-Electrical Characteristic Testing System

Specifically designed for rapid wafer testing, including defect detection, precision calibration, motion control, optical inspection, electrical inspection, etc. The system supports automatic loading and unloading. It can test 25-50 wafers each time and classify wafers based on performance test results to ensure that good chips are used for subsequent production and processing. Thereby greatly reducing post-chip testing, packaging costs and improving the efficiency of the entire assembly line.



Full automated wafer defect tester based on AI self-learning correlations

Defect Types	Scratch, crack, discoloring, debris, DIM errors
Defect Capture Rate	99%
Missing Report Rate	<1%
Wrong Report Rate	<1%
Inspection Time (full wafer)	<15min

Opto-electronic full automated wafer tester

Calibration	Visual AI assisted full automated calibration.
Production testing	Full automated wafer loader, 25 to 50 wafers/lot.
Full Automated Opto-Electronic Testing	Optical testing resolution: 0.05~0.1dB; Precision and stable system architecture; Electrical accuracy: sub nA Motion resolution: < 50nm; Support micron scale mode size testing.
Cost / Performance	The best fine-tuned system engineered by opto-mechanic and opto-electronic professions for best performance at affordable cost. Performance overbeats industrial similar tools, while saving the user capital and facility investment. System is proven to be robust with multiple functional extension capabilities and friendly user interfaces.

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